EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	423	((laser beam light irradiat$5) near2 transmit$5) with ((laser beam light irradiat$5) near2 (reflect$4)) with (measur$4 sens$4) with both	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/17 08:14
L2	252	((laser beam light irradiat$5) near2 through) with ((laser beam light irradiat$5) near2 (reflect$4)) with (measur$4 sens$4) with both	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/17 08:14
L3	583	L1 L2	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/17 08:14
L4	124335	"219"/$.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/17 08:14
L5	182797	"29"/$.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/17 08:14
L6	87047	"72"/$.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/17 08:14
L7	496218	(glass ceramic semiconductor silicon).clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/17 08:14
L8	858575	L4 L5 L6 L7	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/17 08:14
L9	67	L3 and L8	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/17 08:14

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L10	67	L9	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/17 08:15
L11	35	10 and ((laser beam) with (front reflect$4)) same ((laser beam) with (through$4 pass$4 opposite back))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/17 08:57
L12	17	10 and (laser beam) with (cut cutting drill$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/17 08:41
L13	15	10 and (laser beam) with (cut cutting drill$4) and ((laser beam) with (front reflect$4))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/17 08:41
L14	15	12 and (laser beam) with (cut cutting drill$4) and ((laser beam) with (front reflect$4))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/17 08:42
L15	13	12 and (laser beam) with (cut cutting drill$4) and ((laser beam) with (through$4 pass$4 opposite back))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/17 09:22
L16	13	14 and 15	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/17 08:42
L17	2	(("6888853") or ("6086366")).PN.	USPAT; USOCR	OR	OFF	2006/08/17 08:57
L18	2	"20030074096"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/17 08:57
L19	4	17 18	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/17 08:58

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L20	9	12 and (laser beam) near5 (cut cutting drill$4) and ((laser beam) with (through$4 pass$4 opposite back)) same ((laser beam) with (front reflect$4))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/17 09:28
L21	8269	(laser beam) near5 (cut cutting drill$4) and ((laser beam) with (through$4 pass$4 opposite back)) same ((laser beam) with (front reflect$4))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/17 09:28
L22	4305	(laser near5 (cut cutting drill$4)) and (laser with (through$4 pass$4 opposite back)) same (laser with (front reflect$4))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/17 09:29
L23	628	(laser near5 (cut cutting drill$4) with (silicon brittle ceramic semiconductor wafer)) and (laser with (through$4 pass$4 opposite back)) same (laser with (front reflect$4))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/17 09:30
L24	145	(laser near5 (cut cutting drill$4) with (silicon brittle ceramic semiconductor wafer)) and (laser with through$4 near5 pass$4) same (laser near7 reflect$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/17 09:31
L25	0	(laser near5 (cut cutting drill$4) with (silicon brittle ceramic semiconductor wafer)) and (laser with through$4 near5 pass$4 with (aperture cut cutting drill$4 etch$4)) same (laser near7 reflect$4 with surface)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/17 09:31
L26	30	(laser near5 (cut cutting drill$4) with (silicon brittle ceramic semiconductor wafer)) and (laser with through$4 with (aperture cut cutting drill$4 etch$4)) same (laser near7 reflect$4 with surface)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/17 09:32

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Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S53	39009	(laser beam light irradiat$5) with (measur$4 sens$4) with (through$4 pass$4 transmit$5) with (reflect$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/16 11:52
S54	27218	((laser beam light irradiat$5) near5 (through$4 pass$4 transmit$5)) with ((laser beam light irradiat$5) near5 (reflect$4)) with (measur$4 sens$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/16 11:53
S55	16129	((laser beam light irradiat$5) near2 (through$4 pass$4 transmit$5)) with ((laser beam light irradiat$5) near2 (reflect$4)) with (measur$4 sens$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/16 11:58
S56	112726	laser with (machining cutting drilling etching welding melting)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/16 11:55
S57	430	S55 and S56	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/16 11:55
S58	4220	laser with (machining cutting drilling etching welding melting) with (measur$4 sens$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/16 12:09
S59	115	S55 and S58	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/16 11:56
S60	44	((laser beam light irradiat$5) near2 (through$4 pass$4 transmit$5) near5 (work workpiece)) with ((laser beam light irradiat$5) near2 (reflect$4) near5 (work workpiece)) with (measur$4 sens$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/16 12:01
S61	5	S60 and S58	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/16 12:00

S62	7410	((laser beam light irradiat$5) near2 through) with ((laser beam light irradiat$5) near2 (reflect$4)) with (measur$4 sens$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/16 12:05
S63	69	S58 and S62	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/16 12:02
S64	9106	((laser beam light irradiat$5) near2 transmit$5) with ((laser beam light irradiat$5) near2 (reflect$4)) with (measur$4 sens$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/16 12:05
S65	52	S58 and S64	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/16 12:04
S66	105	S63 S65	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/16 12:04
S67	422	((laser beam light irradiat$5) near2 transmit$5) with ((laser beam light irradiat$5) near2 (reflect$4)) with (measur$4 sens$4) with both	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/16 12:05
S68	252	((laser beam light irradiat$5) near2 through) with ((laser beam light irradiat$5) near2 (reflect$4)) with (measur$4 sens$4) with both	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/16 12:12
S69	582	S67 S68	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/16 12:06
S70	6	S58 and S69	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/16 12:06
S71	124327	"219"/$.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/16 12:10

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S72	182748	"29"/$.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/16 12:10
S73	87036	"72"/$.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/16 12:11
S74	495650	(glass ceramic semiconductor silicon).clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/16 12:11
S75	857957	S71 S72 S73 S74	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/16 12:11
S76	67	S69 and S75	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/17 08:14